

**ADVANCE DATA SHEET**

# SKY77435 Front-End Module for WCDMA / HSDPA / HSUPA (Tx 1710-1770 MHz), (Rx 2110-2170 MHz)

**Applications**

- Digital cellular (WCDMA) handsets

**Features**

- High Speed Downlink Packet Access (HSDPA)
- High Speed Uplink Packet Access (HSUPA)
- Low quiescent current - 20 mA
- Low current consumption - 530 mA
- Integrated Power Detector
- 16-pad package
- Small profile - 7 mm x 4 mm x 1.1 mm
- Low voltage - 3.1 V–4.45 V
- Digital enable pad
- Highly integrated, user friendly solution
- InGaP HBT
- Integrated interstage filter and duplexer
- Requires few external components

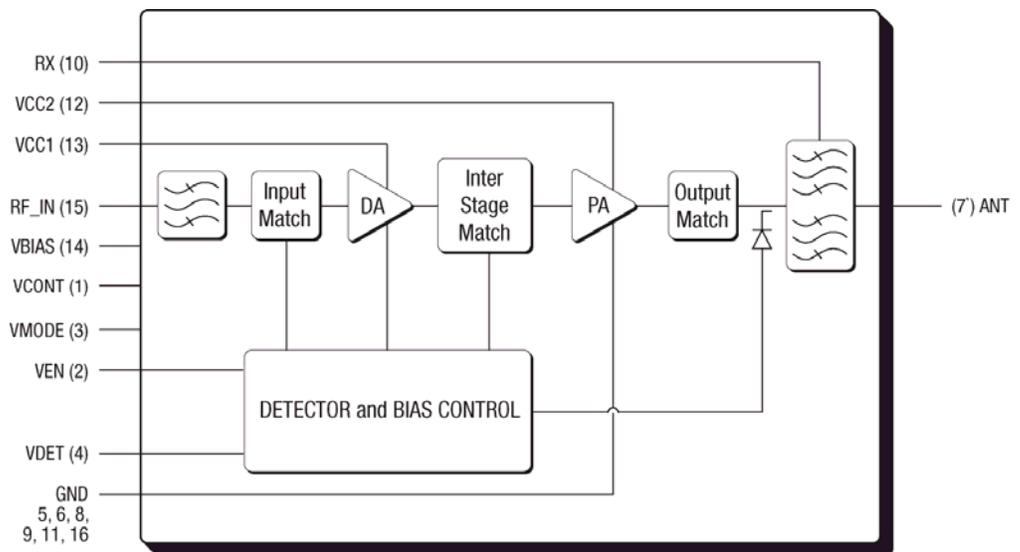
**Description**

The SKY77435 Front-End Module (FEM) is a fully matched, 16-pad surface mount module developed for WCDMA applications. Small and efficient, this WCDMA FEM integrates the interstage filter, the input matching, the power amplifier, the output matching, the power detection, and the duplexer into a single 7 mm x 4 mm x 1.1 mm package.

The SKY77435 meets the stringent spectral requirements of HSDPA standards up to 25.2 dBm output power. The FEM incorporates an InGaP HBT PA and contains circuitry to optimize power detector performance. Different control pads are available to enhance the performance of the FEM at different power levels.

Integration of the RF front-end greatly simplifies the design of the handset radio as all critical matching between the interstage filter, PA, power detection, and duplexer is optimized within the module. By optimizing the efficiency of the InGaP HBT PA MMIC and reducing the RF loss between the integrated components, this FEM achieves current as low as 450 mA at maximum output power (25.2 dBm) that significantly improves the talk time of the WCDMA handset. This small package uses Skyworks' low cost, multi-laminate substrate technology and is approximately half the size of individually packaged component solutions. The SKY77435 front-end module can save handset designers significant board space and design-cycle time.

**NEW** Skyworks Green™ products are lead (Pb)-free, RoHS (Restriction of Hazardous Substances)-compliant, conform to the EIA/EICTA/JEITA Joint Industry Guide (JIG) Level A guidelines, and are free from antimony trioxide and brominated flame retardants.

**Figure 1. Functional Block Diagram**

**Electrical Specifications**

The following tables list the electrical characteristics of the SKY77435 Front-End Module for WCDMA. [Table 1](#) lists the absolute maximum ratings and [Table 2](#) specifies the recommended operating conditions necessary to achieve the electrical performance listed in [Table 3](#). [Table 4](#) through [Table 7](#)

defines the standard test configurations for WCDMA, HSDPA, and HSUPA modes. [Table 8](#) provides specifications for Power Detection. [Table 9](#) and [Table 10](#) specifies the Nominal Duplexer Performance for Band IV and Band X, respectively..

**Table 1. Absolute Ratings<sup>1</sup>**

Parameter	Symbol	Minimum	Nominal	Maximum	Unit	
RF Input Power	P <sub>IN</sub>	—	—	10.0	dBm	
Supply Voltages	No RF	V <sub>CC1</sub> , V <sub>CC2</sub> , V <sub>BIAS</sub>	—	3.4	6.0	Volt
	With RF		—	3.4	4.7	Volt
Bias Control Voltage	V <sub>CONT</sub>	—	—	2.7	Volt	
Mode Control Voltage	V <sub>MODE</sub>	—	—	3.0	Volts	
Enable Control Voltage	V <sub>EN</sub>	—	—	3.0	Volt	
Temperatures	Operating	T <sub>CASE</sub>	-20	+25	+110	°C
	Storage	T <sub>STG</sub>	-55	—	+125	

<sup>1</sup> No damage assuming only one parameter at a time is set to limit with all other parameters set at nominal values.

**Table 2. Recommended Operating Conditions**

Parameter	Symbol	Minimum	Nominal	Maximum	Unit	
Tx Channel Center Frequency	F <sub>TX</sub>	1712.4	1740.0	1767.6	MHz	
Rx Channel Center Frequency	F <sub>RX</sub> = F <sub>TX</sub> + 400 MHz	2112.4	2140.0	2167.6	MHz	
Supply Voltages	V <sub>CC1</sub> , V <sub>CC2</sub>	3.1 <sup>1</sup>	3.4	4.45	Volt	
	V <sub>BIAS</sub>	3.1	3.4	4.45		
Bias Control Voltage	V <sub>CONT</sub>	0.5	—	1.9	Volt	
Mode Control	Low Power Mode (LPM)	V <sub>MODE_L</sub>	1.5	1.8	2.85	Volt
	High Power Mode (HPM)	V <sub>MODE_H</sub>	0.0	0.0	0.56	
Enable Control Setting	Disabled	V <sub>EN_L</sub>	0.0	0.0	0.56	Volt
	Enabled	V <sub>EN_H</sub>	1.5	1.8	2.85	
Operating Temperature	T <sub>CASE</sub>	-20	+25	+85	°C	

<sup>1</sup> For V<sub>CC</sub> < 3.4 V, maximum output power = P<sub>MAX2</sub>

**Table 3. Electrical Specifications for Nominal Operating Conditions <sup>1</sup>**

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Unit		
Linear Output Power	P <sub>MID</sub>	HPM, LPM V <sub>CC</sub> ≥ 3.1 V	10.0	—	—	dBm		
	P <sub>MAX2</sub>	HPM V <sub>CC</sub> ≥ 3.1 V	24.4	—	—			
	P <sub>MAX1</sub>	HPM	25.2	—	—			
Gain	Mid Power	G <sub>MID</sub>	LPM P <sub>MID</sub>	11.0	—	23.0	dB	
	High Power	G <sub>HIGH</sub>	V <sub>CC</sub> = 3.4 V P <sub>MAX1</sub> T <sub>CASE</sub> = 25 °C	19.5	—	28.5		
Gain Flatness Over Frequency	ΔG <sub>PWR</sub>	Each Tx Frequency	-2.5	—	2.5	dB		
Current Consumption	Band IV	Mid Power	I <sub>CC</sub>	LPM P <sub>MID</sub>	—	—	50	mA
		High Power		P <sub>MAX1</sub>	—	—	530	
	Band X	Mid Power		LPM P <sub>MID</sub>	—	—	50	
		High Power		P <sub>MAX1</sub>	—	—	530	
Power Added Efficiency	Band IV	Mid Power	PAE <sub>MID</sub>	LPM P <sub>MID</sub>	5.4	—	—	%
		High Power	PAE <sub>HIGH</sub>	P <sub>MAX1</sub>	18.4	—	—	
	Band X	Mid Power	PAE <sub>MID</sub>	LPM P <sub>MID</sub>	5.4	—	—	
		High Power	PAE <sub>HIGH</sub>	P <sub>MAX1</sub>	18.4	—	—	
Error Vector Magnitude	EVM	—	—	—	5	%		
Adjacent Channel Leakage Ratio <sup>2</sup>	5 MHz	ACL1	—	—	-40	—	dBc	
	10 MHz	ACL2	—	—	-54	—		
Harmonic Suppression	Second	2f <sub>0</sub>	P <sub>MAX1</sub>	—	—	-33	dBm	
	Third	3f <sub>0</sub>		—	—	-33		
Tx Noise Power in Rx Band	NRx1	P <sub>MAX1</sub> 869–894 MHz RBW = 3.84 MHz	—	—	-61	dBm		
	NRx2	P <sub>MAX1</sub> 1575.42 MHz RBW = 2.046 MHz	—	—	-100			
	NRx3	P <sub>MAX1</sub> 1930–1990 MHz RBW = 3.84 MHz	—	—	-61			
	NRx4	P <sub>MAX1</sub> 2110–2170 MHz RBW = 3.84 MHz	—	—	-114			
	NRx5	P <sub>MAX1</sub> 2400–2483.5 MHz RBW = 1.0 MHz	—	—	-90			

**Table 3. [continued] Electrical Specifications for Nominal Operating Conditions<sup>1</sup>**

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Input Voltage Standing Wave Ratio	VSWR	—	—	—	2:1	
Quiescent Current	I <sub>Q</sub>	—	—	—	18	mA
Control Current	I <sub>BA</sub>	—	—	—	1	mA
Digital Enable Current	I <sub>EN</sub>	—	—	—	1	mA
Leakage Current	I <sub>LEAK</sub>	V <sub>CC1</sub> , V <sub>CC2</sub> , V <sub>BIAS</sub> = 4.45 V V <sub>CONT</sub> = 0 V V <sub>EN</sub> = 0.2 V V <sub>MODE_H</sub> = 0 V	—	—	20	μA
Stability (spurious output)	S	8:1 VSWR, all phases	—	—	-65	dBc
Ruggedness <sup>3</sup>	R <sub>u</sub>	—	10:1	—	—	

<sup>1</sup> Unless otherwise specified: V<sub>CC</sub> = 3.4 V, Temp. = 25 °C.

<sup>2</sup> For STC1 WCDMA, STC2 HSDPA, and STC3 HSUPA modes test conditions. For STC4 HSUPA, power back off = 2.6 dB.

<sup>3</sup> ACLR is specified per 3GPP as the ratio of in-band power to adjacent power, both measured in 3.84 MHz bandwidth at specified offsets.

<sup>4</sup> All phases, time = 10 seconds, continuous WCDMA/HSDPA modulated signal.

**Table 4. Standard Test Configuration – STC1 WCDMA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	β <sub>c</sub>	β <sub>d</sub>	β <sub>hs</sub>	β <sub>ec</sub>	β <sub>ed</sub>	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	-6.547
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	-1.087

**Table 5. Standard Test Configuration – STC2 HSDPA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	β <sub>c</sub>	β <sub>d</sub>	β <sub>hs</sub>	β <sub>ec</sub>	β <sub>ed</sub>	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	12/15	—	—	—	—	-7.095
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	-5.157
HS-DPCCH	15 kbps	64	256	Q	—	—	24/15	—	—	-3.012

**Table 6. Standard Test Configuration – STC3 HSUPA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	β <sub>c</sub>	β <sub>d</sub>	β <sub>hs</sub>	β <sub>ec</sub>	β <sub>ed</sub>	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	-19.391
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	-13.931
HS-DPCCH	15 kbps	64	256	Q	—	—	8/15	—	—	-19.391
E-DPCCH	15 kbps	1	256	I	—	—	—	10/15	—	-17.338
E-DPDCH	960 kbps	2	4	I	—	—	—	—	71.5/15	-0.371

**Table 7. Standard Test Configuration – STC4 HSUPA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	$\beta_c$	$\beta_d$	$\beta_{hs}$	$\beta_{ec}$	$\beta_{ed}$	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	6/15	—	—	—	—	-12.499
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	-4.540
HS- DPCCH	15 kbps	64	256	Q	—	—	2/15	—	—	-22.041
E-DPCCH	15 kbps	1	256	I	—	—	—	12/15	—	-6.478
E-DPDCH	960 kbps	2	4	I	—	—	—	—	15/15	-4.425

**Table 8. Electrical Specifications for Power Detector**

Tx Power Detection						
Characteristic	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Power Detect Range	P <sub>DET</sub>		0.0	—	26.2	dBm
Detector Output Range	V <sub>DET</sub>	3 dBm ≤ P <sub>0</sub> ≤ 26.2 dBm	400 (rms)	—	1800 (peak)	mV

**Table 9. Nominal Duplexer Performance – Band IV7**

Antenna to Rx Parameter						
Characteristic	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Insertion Loss	IL <sub>Rx</sub>	2110 MHz...2170 MHz	—	—	2.5	dB
Ripple		Each Rx Frequency	-0.5	—	0.5	dB
Attenuation		DC...12750 MHz	20	—	—	dB
		AR <sub>x1</sub>	390 MHz...410 MHz	40	—	
		AR <sub>x2</sub>	703 MHz...724 MHz	30	—	
		AR <sub>x3</sub>	1055 MHz...1085 MHz	45	—	
		AR <sub>x4</sub>	1310 MHz...1370 MHz	35	—	
	Tx Band	AR <sub>x5</sub>	1710 MHz...1770 MHz	50	—	
		AR <sub>x6</sub>	1910 MHz...1970 MHz	25	—	
		AR <sub>x7</sub>	3820 MHz...3940 MHz	35	—	
	AR <sub>x8</sub>	5530 MHz...5710 MHz	35	—	—	
VSWR		—	—	—	2.0:1	
Input		—	—	—	30	dBm
Tx Power @ Rx Port		1710 MHz...1770 MHz P <sub>MAX1</sub>	—	—	-25	dBm

**Table 10. Nominal Duplexer Performance – Band X8**

Antenna to Rx Parameter						
Characteristic	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Insertion Loss	IL <sub>Rx</sub>	2110 MHz...2170 MHz	—	—	2.8	dB
Ripple		Each Rx Frequency	-0.5	—	0.5	dB
Attenuation		DC...12750 MHz	20	—	—	dB
		AR <sub>x1</sub>	390 MHz...410 MHz	40	—	
		AR <sub>x2</sub>	703 MHz...724 MHz	30	—	
		AR <sub>x3</sub>	1055 MHz...1085 MHz	45	—	
		AR <sub>x4</sub>	1310 MHz...1370 MHz	35	—	
	Tx Band	AR <sub>x5</sub>	1710 MHz...1770 MHz	50	—	
		AR <sub>x6</sub>	1910 MHz...1970 MHz	25	—	
	Tx + Rx	AR <sub>x7</sub>	3820 MHz...3940 MHz	35	—	
2Tx + Rx	AR <sub>x8</sub>	5530 MHz...5710 MHz	35	—	—	
VSWR		—	—	—	2.0:1	
Input		—	—	—	30	dBm
Tx Power @ Rx Port		1710 MHz...1770 MHz P <sub>MAX1</sub>	—	—	-25	dBm

### Evaluation Board Description

The evaluation board is a platform for testing and interfacing design circuitry. To accommodate the interface testing of the SKY77435, the evaluation board schematic and the basic

assembly diagram are included for preliminary analysis and design. Figure 2 is a simple schematic of the board assembly in Figure 3.

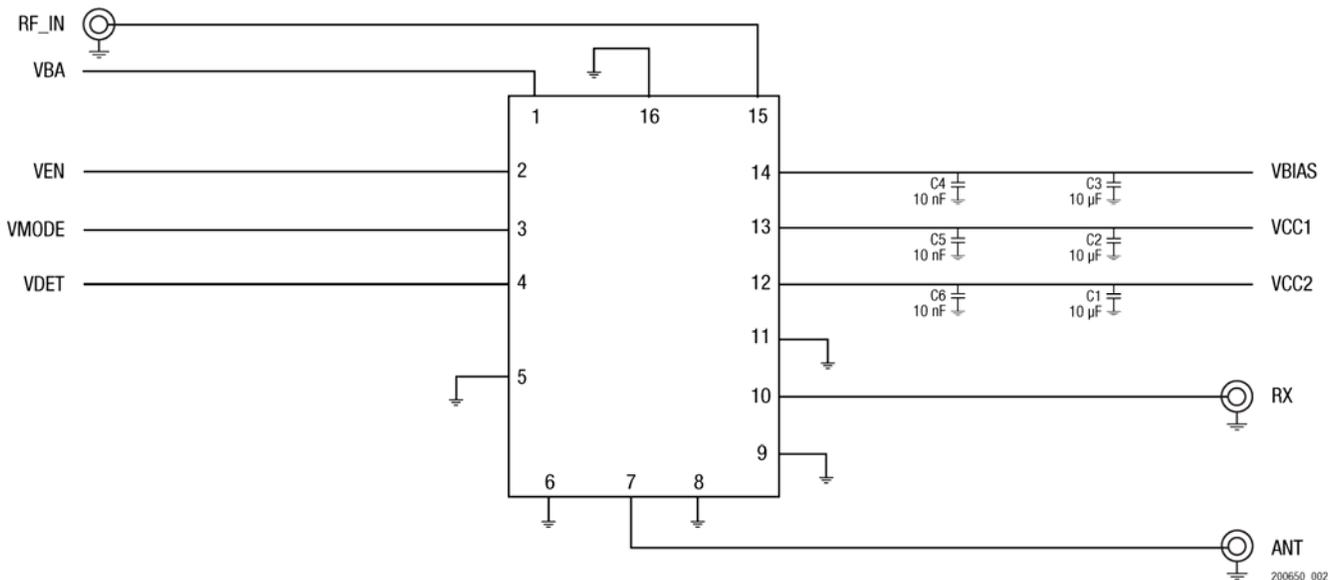


Figure 2. SKY77435 Evaluation Board Schematic Diagram

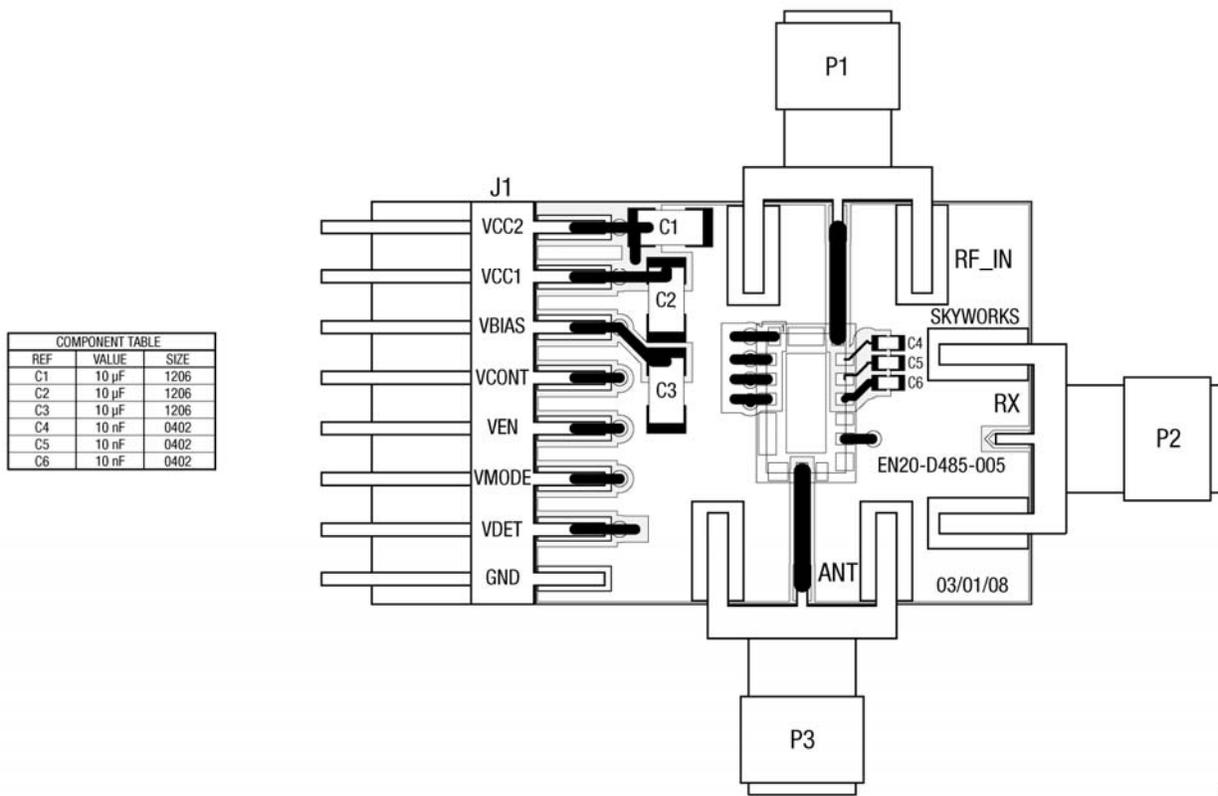
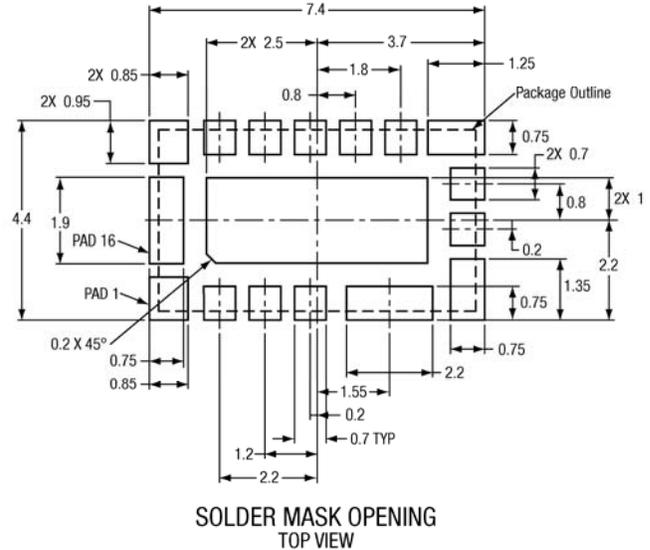
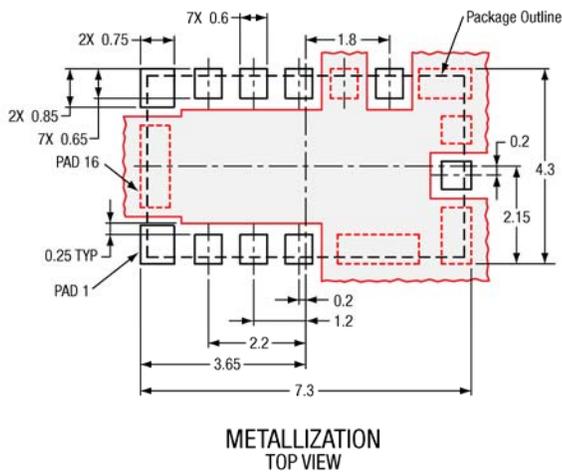
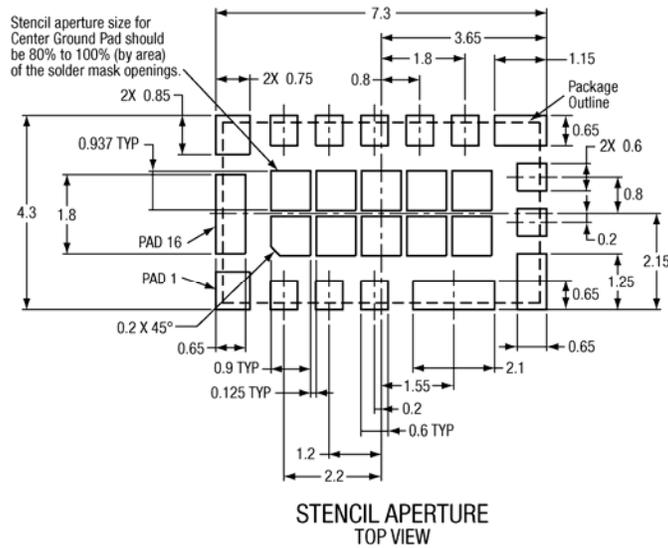


Figure 3. SKY77435 Evaluation Board Assembly Diagram





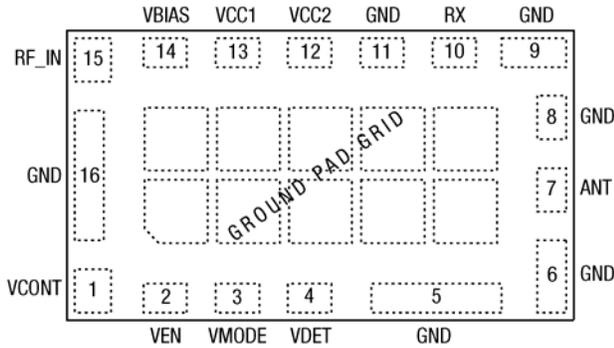
- NOTES: UNLESS OTHERWISE SPECIFIED.
1. DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ASME Y14.5M-1994.
  2. ALL DIMENSIONS ARE IN MILLIMETERS.

DS00089-2 REV. 1  
200650\_005

Figure 5. Phone PCB Layout Footprint for 7 x 4 mm, 16-Pad Package – SKY77435

**Package Description**

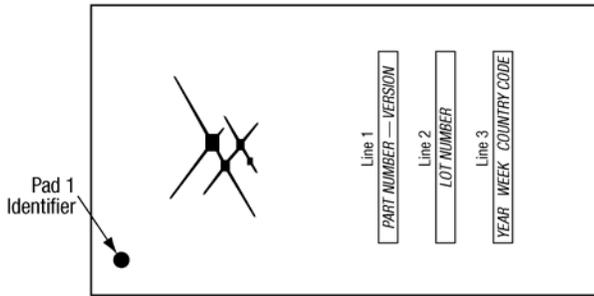
Figure 6 shows each pad name and the pad numbering convention, which starts with pad 1 in the upper left, as indicated and increments counter-clockwise around the package. Figure 7 illustrates typical case markings.



Pad layout as seen from Top View looking through package.

200650\_006

**Figure 6. SKY77435 16-Pad Configuration – (Top View)**



NOTE: SKY77435  
Lines 1, 2, 3 have a maximum of 11 characters  
YEAR = Year of Manufacture  
WEEK = Week Package Was Sealed  
Country Code = Country of Manufacture (MX)

200650\_006

**Figure 7. Typical Case Markings (Top View)**

**Package Handling Information**

Because of its sensitivity to moisture absorption, this device package is baked and vacuum-packed prior to shipment. Instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken, otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY77435 is currently qualified for MSL3/260 °C. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is attached in a reflow oven, the temperature ramp rate should not exceed 3 °C per second; maximum temperature should not exceed 260 °C. If the part is manually attached, precaution should be taken to insure that the part is not subjected to temperatures exceeding 260 °C for more than 10 seconds. For details on attachment techniques, precautions, and handling procedures recommended by Skyworks, please refer to Skyworks Application Note: *PCB Design and SMT Assembly/Rework*, Document Number 101752. Additional information on standard SMT reflow profiles can also be found in the *JEDEC Standard J-STD-020*.

Production quantities of this product are shipped in the standard tape-and-reel format. For packaging details, refer to Skyworks Application Note: *Tape and Reel – RF Modules*, Document Number 101568.

**Electrostatic Discharge Sensitivity (ESD)**

To avoid ESD damage, both latent and visible, it is very important that the product assembly and test areas follow the Class 1 ESD handling precautions listed below.

- Personnel Grounding
  - Wrist Straps
  - Conductive Smocks, Gloves and Finger Cots
  - Antistatic ID Badges
- Protective Workstation
  - Dissipative Table Top
  - Protective Test Equipment (Properly Grounded)
  - Grounded Tip Soldering Irons
  - Solder Conductive Suckers
  - Static Sensors
- Facility
  - Relative Humidity Control and Air Ionizers
  - Dissipative Floors (less than 10<sup>9</sup> Ω to GND)
- Protective Packaging and Transportation
  - Bags and Pouches (Faraday Shield)
  - Protective Tote Boxes (Conductive Static Shielding)
  - Protective Trays
  - Grounded Carts
  - Protective Work Order Holders

## Ordering Information

Model Number	Manufacturing Part Number	Product Revision	Package	Operating Temperature
SKY77435	SKY77435		MCM 4 x 7 x 1.1 mm	-20 °C...+85 °C

## Revision History

Revision	Date	Description
A	December 2, 2008	Initial Release – Advance Information

## References

Skyworks Application Note: Tape and Reel – RF Modules, Document Number 101568

Skyworks Application Note: PCB Design and SMT Assembly/Rework, Document Number 101752

JEDEC Standard J-STD-020

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